

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method of a ~~display~~ device in a plasma treatment chamber comprising the step of:

forming a wiring by partially etching a conductor film over a substrate by discharging a plasma to the plasma treatment chamber from a plasma treatment means having one set of electrodes contained therein for generating the plasma at a pressure of 5 to 800 Torr from a reactive gas introduced to the plasma treatment means,

wherein the plasma treatment means is provided in the plasma treatment chamber, and wherein one electrode of the set of electrodes surrounds the other electrode of the set of electrodes.

2. (Currently Amended) A manufacturing method of a ~~display~~ device in a plasma treatment chamber comprising the step of:

forming a wiring by partially etching a conductor film over a substrate by discharging a plasma to the plasma treatment chamber from a plasma treatment means having a plurality of sets of electrodes contained therein for generating the plasma at a pressure of 5 to 800 Torr from a reactive gas introduced to the plasma treatment means,

wherein the plasma treatment means is provided in the plasma treatment chamber, and wherein one electrode of the plurality of sets of electrodes surrounds the other electrode of the plurality of sets of electrodes, respectively.

3. (Canceled)

4. (Currently Amended) A manufacturing method of a ~~display~~ device comprising the steps of:

forming a conductor film over a substrate;

forming a resist mask over the conductor film; and
partially etching the conductor film at a pressure of 5 to 800 Torr by discharging a plasma to a plasma treatment chamber from a plasma treatment means having ~~at least~~ one set of electrodes contained therein for generating the plasma from a reactive gas introduced to the plasma treatment means, over the resist mask thereby forming a wiring,

wherein the plasma treatment means is provided in the plasma treatment chamber, and
wherein one electrode of the set of electrodes surrounds the other electrode of the set of electrodes.

5. (Currently Amended) A manufacturing method of a ~~display~~ device comprising the steps of:

forming a conductor film over a substrate;
forming a resist mask over the conductor film; and
partially etching the conductor film at a pressure of 5 to 800 Torr by discharging a plasma to a plasma treatment chamber from a plasma treatment means having a plurality of sets of electrodes contained therein for generating the plasma from a reactive gas introduced to the plasma treatment means, over the resist mask thereby forming a wiring,

wherein the plasma treatment means is provided in the plasma treatment chamber, and
wherein one electrode of the plurality of sets of electrodes surrounds the other electrode of the plurality of sets of electrodes, respectively.

6. (Currently Amended) The manufacturing method of the ~~display~~ device according to any of claims 1, 2, 4 and 5, wherein the substrate has a size of 1,000 x 1,200 mm² or more.

7. (Currently Amended) The manufacturing method of the ~~display~~ device according to any of claims 1, 2, 4 and 5, wherein the plasma treatment means scans the substrate in one direction.

8. (Currently Amended) The manufacturing method of the ~~display~~ device according to

any of claims 1, 2, 4 and 5, wherein the plasma treatment means alternately scans the substrate in a row direction and in a column direction.

9. (Currently Amended) The manufacturing method of the ~~display~~ device according to any of claims 4 and 5, wherein the resist mask is formed by use of liquid droplet jetting means.

10-11. (Canceled)

12. (Currently Amended) The manufacturing method of the ~~display~~ device according to any of claims 1, 2, 4 and 5, further comprising:
moving the plasma treatment means along a rail.